

DATE: 23rd January, 2012

PCN #: 2062

PCN Title: Qualification of Additional Wafer Source and Additional Top Metal

Wafer Process

Dear Customer:

This is an announcement of change(s) to products that are currently being offered by Diodes Incorporated.

We request that you acknowledge receipt of this notification within 30 days of the date of this PCN. If you require samples for evaluation purposes, please make a request within 30 days as well. Otherwise, samples may not be built prior to this change. Please refer to the implementation date of this change as it is stated in the attached PCN form. Please contact your local Diodes sales representative to acknowledge receipt of this PCN and for any sample requests.

The changes announced in this PCN will not be implemented earlier than 90 days from the notification date stated in the attached PCN form.

Previously agreed upon customer specific change process requirements or device specific requirements will be addressed separately.

For questions or clarification regarding this PCN, please contact your local Diodes sales representative.

Sincerely,

Diodes Incorporated PCN Team

Rel Date: 04/28/2010



PRODUCT CHANGE NOTICE

PCN-2062- REV00

Rel Date: 04/28/2010

Notification Date:	Implementation Date:	Product Family:	Change Type:	PCN #:
23 rd January, 2012	22 nd April, 2012	Discrete Semiconductors	Wafer FAB Material and Wafer Fabrication Site	2062

TITLE

Qualification of Additional Wafer Source and Additional Top Metal Wafer Process

DESCRIPTION OF CHANGE

Additional, equivalent wafer fab and fabrication processes have been established and qualified to ensure continuity of supply.

- For select part numbers in PowerDI[®]123, PowerDI[®]5, SMA packages (see table 1):
 - o Qualification of CSMC in addition to the currently qualified wafer fabrication sources
 - Qualification of an additional solderable top metal process at the current wafer fabrication site, Diodes internal Oldham Fab (OFAB)
- For select part numbers in TO-220AB packages (see table 2):
 - Qualification of an additional solderable top metal process at the current wafer fabrication site, Diodes internal Oldham Fab (OFAB)

Affected products are listed in the attached tables.

Full electrical characterization and high reliability testing has been completed on representative parts to ensure no change to device functionality or data sheet electrical specifications.

There is no change to Form, Fit, or Function of affected products.

IMPACT				
None				
PRODUCTS AFFECTED				
Please refer to the attached tables below.				
WEB LINKS				
Manufacturer's Notice:	http://www.diodes.com/quality/pcns			
For More Information Contact:	http://www.diodes.com/contacts			
Data Sheet:	http://www.diodes.com/products			
DISCLAIMER				

Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.



Table 1

Affected Part Numbers in PowerDI®123, PowerDI®5, SMA					
SBR1U200P1-7	SBR1045SP5-13	SBR1A40SA-13			
SBR1U400P1-7	SBR10A45SP5-13	SBR1U150SA-13			
SBR2A30P1-7	SBR10U200P5-13	SBR2A40SA-13			
SBR2A40P1-7	SBR10U45SP5-13	SBR2U150SA-13			
SBR2M30P1-7	SBR12A45SP5-13	SBR2U30SA-13			
SBR2U30P1-7	SBR12U100P5-13	SBR3A40SA-13			
SBR3M30P1-7	SBR12U120P5-13	SBR3U20SA-13			
SBR3U30P1-7	SBR8A45SP5-13	SBR3U20SA-13			
SBR3U40P1-7	SBR8U60P5-13	SBR3U20SA-13			
SBR3U60P1-7	SBR15U30SP5-13				

Table 2

Affected Part Numbers in TO-220AB					
SBR20A100CT	SBR20A40CT	SBR20100CT			
SBR20A100CT-G	SBR20A40CT-G	SBR20100CT-G			

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